# **Single 2-Input NOR Gate**

The NL17SG02 MiniGate<sup>™</sup> is an advanced high-speed CMOS 2-input NOR gate in ultra-small footprint.

The NL17SG02 input structures provides protection when voltages up to 4.6 V are applied.

### **Features**

- Wide Operating V<sub>CC</sub> Range: 0.9 V to 3.6 V
- High Speed:  $t_{PD}$  = 2.4 ns (Typ) at V<sub>CC</sub> = 3.0 V, C<sub>L</sub> = 15 pF
- Low Power Dissipation:  $I_{CC} = 0.5 \ \mu A$  (Max) at  $T_A = 25^{\circ}C$
- 4.6 V Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Packages
- These are Pb-Free and Halide-Free Devices



# **ON Semiconductor®**

http://onsemi.com

### MARKING DIAGRAM





= Specific Device Code 5 М = Month Code

SOT-953

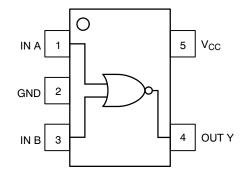
PIN ASSIGNMENT				
1	IN A			
2	GND			
3	IN B			
4	OUT Y			
5	V <sub>CC</sub>			

### **FUNCTION TABLE**

Inp	uts	Output
Α	в	Y
L	L	Н
L	н	L
н	L	L
Н	Н	L

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.





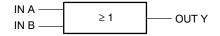


Figure 2. Logic Symbol

### **MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +5.5	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +4.6	V
V <sub>OUT</sub>	DC Output Voltage	Output at High or Low State Power-Down Mode (V <sub>CC</sub> = 0 V)	-0.5 to V <sub>CC</sub> +0.5 -0.5 to +4.6	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	-20	mA
I <sub>OUT</sub>	DC Output Source/Sink Current		±20	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±20	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±20	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Secon	ds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
$V_{\text{ESD}}$	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V
ILATCHUP	Latchup Performance Above V <sub>C</sub>	<sub>CC</sub> and Below GND at 125°C (Note 4)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
Tested to EIA/JESD22-A114-A.

3. Tested to EIA/JESD22-A115-A.

4. Tested to EIA/JESD78.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Characteristics	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	0.9	3.6	V
V <sub>IN</sub>	Digital Input Voltage	0.0	3.6	V
V <sub>OUT</sub>	Output Voltage Output at High or Low State Power–Down Mode (V <sub>CC</sub> = 0 V)	0.0 0.0	V <sub>CC</sub> 3.6	V
T <sub>A</sub>	Operating Temperature Range	-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fail Rate $V_{CC}$ = 3.3 V ± 0.3 V	0	10	ns/V

### DC ELECTRICAL CHARACTERISTICS

					T <sub>A</sub> =	25°C		. = 0 +125°C		
Symbol Parameter	Parameter	ter Conditions	onditions	V <sub>CC</sub> (V)	Min	Max	Min	Max	Unit	
VIH	High-Level Input			0.9	V <sub>CC</sub>		V <sub>CC</sub>		V	
	Voltage			1.1 to 1.3	0.7xV <sub>CC</sub>		0.7xV <sub>CC</sub>			
				1.4 to 1.6	0.65xV <sub>CC</sub>		0.65xV <sub>CC</sub>			
				1.65 to 1.95	0.65xV <sub>CC</sub>		0.65xV <sub>CC</sub>			
				2.3 to 2.7	1.7		1.7			
				3.0 to 3.6	2.0		2.0			
V <sub>IL</sub>	Low-Level Input			0.9		GND		GND	V	
	Voltage			1.1 to 1.3		0.3xV <sub>CC</sub>		0.3xV <sub>CC</sub>		
				1.4 to 1.6		0.35xV <sub>CC</sub>		0.35xV <sub>CC</sub>		
				1.65 to 1.95		0.35xV <sub>CC</sub>		0.35xV <sub>CC</sub>		
				2.3 to 2.7		0.7		0.7		
				3.0 to 3.6		0.8		0.8		
V <sub>OH</sub>	High-Level	-	V <sub>IN</sub> =	I <sub>OH</sub> = -20 μA	0.9	0.75		0.75		V
	Output Voltage	utput Voltage V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -0.3 mA	1.1 to 1.3	0.75xV <sub>CC</sub>		0.75xV <sub>CC</sub>			
			I <sub>OH</sub> = -1.7 mA	1.4 to 1.6	0.75xV <sub>CC</sub>		0.75xV <sub>CC</sub>			
			I <sub>OH</sub> = -3.0 mA	1.65 to 1.95	Vcc-0.45		Vcc-0.45			
			I <sub>OH</sub> = -4.0 mA	2.3 to 2.7	2.0		2.0			
			I <sub>OH</sub> = -8.0 mA	3.0 to 3.6	2.48		2.48			
V <sub>OL</sub>	Low-Level	V <sub>IN</sub> =	I <sub>OL</sub> = 20 μA	0.9		0.1		0.1	V	
	Output Voltage	V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 0.3 mA	1.1 to 1.3		0.25xV <sub>CC</sub>		0.25xV <sub>CC</sub>		
			I <sub>OL</sub> = 1.7 mA	1.4 to 1.6		0.25xV <sub>CC</sub>		0.25xV <sub>CC</sub>		
			I <sub>OL</sub> = 3.0 mA	1.65 to 1.95		0.45		0.45		
			I <sub>OL</sub> = 4.0 mA	2.3 to 2.7		0.4		0.4		
			I <sub>OL</sub> = 8.0 mA	3.0 to 3.6		0.4		0.4		
I <sub>IN</sub>	Input Leakage Current	0 ≤	V <sub>IN</sub> ≤ 3.6 V	0 to 3.6		±0.1		±1.0	μA	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =	V <sub>CC</sub> or GND	3.6		0.5		10.0	μA	

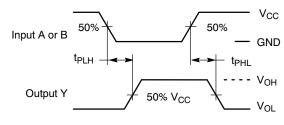
# NL17SG02

Symbol Parameter		Test Condition	V <sub>CC</sub> (V)	1	T <sub>A</sub> = 25° C		T <sub>A</sub> = -55°C to +125°C				
-			Min	Тур	Max	Min	Max	Unit			
t <sub>PLH</sub> ,	Propagation Delay,	$C_L = 10 \text{ pF},$	0.9	-	12.5	14.8	-	16.0	ns		
t <sub>PHL</sub>	A or B to Y	$R_{L} = 1 M\Omega$	1.1 to 1.3	-	8.8	11.4	-	13.2			
			1.4 to 1.6	-	5.0	8.5	-	10.0			
			1.65 to 1.95	-	3.8	6.2	-	6.7			
			2.3 to 2.7	-	2.7	3.9	-	4.4			
			3.0 to 3.6	-	2.1	3.1	-	3.7			
		C <sub>L</sub> = 15 pF,	0.9	-	13.7	15.5	-	17.3	ns		
		R <sub>L</sub> = 1 ΜΩ	1.1 to 1.3	-	10.6	12.5	-	15.2			
			1.4 to 1.6	-	5.9	9.3	-	11.2			
						1.65 to 1.95	-	4.5	6.9	-	7.1
			2.3 to 2.7	-	3.0	4.4	-	5.0			
			3.0 to 3.6	-	2.4	3.4	-	3.9			
		C <sub>L</sub> = 30 pF,	0.9	-	15.5	17.6	-	20.3	ns		
	$\overrightarrow{R_L} = 1 \ \overrightarrow{M\Omega}$ 1.1 to 1.	1.1 to 1.3	-	11.8	14.6	-	17.0				
			1.4 to 1.6	-	8.0	13.1	-	15.9			
			1.65 to 1.95	-	6.0	9.2	-	9.6			
			2.3 to 2.7	-	3.9	5.7	-	6.1			
			3.0 to 3.6	-	3.0	4.4	-	4.8			
C <sub>IN</sub>	Input Capacitance		0 to 3.6		3	-	-	-	pF		
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	f = 10 MHz	0.9 to 3.6	-	4	-	-	-	pF		

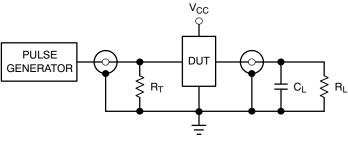
### AC ELECTRICAL CHARACTERISTICS Input $t_r = t_f = 3.0$ ns

5.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no-load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

## NL17SG02







 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 4. Test Circuit

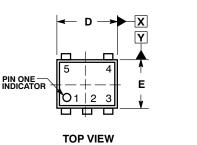
### **ORDERING INFORMATION**

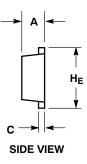
Device	Package	Shipping <sup>†</sup>	
NL17SG02P5T5G	SOT–953 (Pb–Free)	8000 / Tape & Reel	

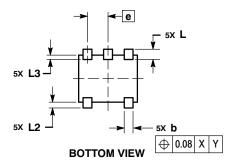
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E

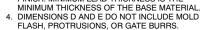






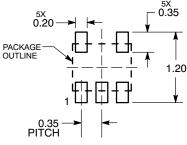
NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.

Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE



	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.34	0.37	0.40		
b	0.10	0.15	0.20		
С	0.07	0.12	0.17		
D	0.95	1.00	1.05		
Е	0.75	0.80	0.85		
е		0.35 BSC			
HE	0.95	1.00	1.05		
L	0.175 REF				
L2	0.05	0.10	0.15		
L3	0.15				

#### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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